

Zero Recovery Silicon Carbide Schottky Diode

PRODUCT APPLICATIONS

- Anti-Parallel Diode

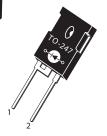
 Switchmode Power Supply
 Inverters
- Power Factor Correction (PFC)

PRODUCT FEATURES

- Zero Recovery Times (t_{rr})
- Popular TO-247 Package
- · Low Forward Voltage
- Low Leakage Current

PRODUCT BENEFITS

- · Higher Reliability Systems
- Minimizes or eliminates snubber





1 - Cathode 2 - Anode Back of Case - Cathode

MAXIMUM RATINGS

All Ratings: T_C = 25°C unless otherwise specified.

Symbol	Characteristic / Test Conditions		Ratings	Unit	
V _R	Maximum D.C. Reverse Voltage				
V _{RRM}	Maximum Peak Repetitive Reverse Voltage		1200	Volts	
V _{RWM}	Maximum Working Peak Reverse Voltage				
	Maximum D.C. Forward Current	T _c = 25°C	43		
I _F		T _c = 163°C	10		
I _{FRM}	Repetitive Peak Forward Surge Current (T _c = 25°C, t _p = 10ms, Half Sine Wave)		50	Amps	
I _{FSM}	Non-Repetitive Forward Surge Current (T _c = 25°C, t _p = 10ms, Half Sine)		110]	
P_{tot}	Power Dissipation	T _C = 25°C	167	W	
		T _c = 110°C	72	l vv	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to 175	°C	
T _L	ead Temperature for 10 Seconds		300		

STATIC ELECTRICAL CHARACTERISTICS

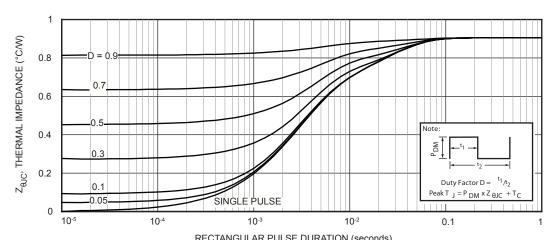
Symbol	Characteristic / Test Conditions		Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 10A T _J = 25°C		1.5	1.8	Volts
		I _F = 10A, T _J = 175°C		2.3		
I _{RM}	Maximum Reverse Leakage Current	V _R = 1200V T _J = 25°C		10	200	μА
		V _R = 1200V, T _J = 175°C		500		
Q _c	Total Capactive Charge V_R = 600V, I_F = 10A, di/dt = -500A/ μ s, T_J = 25°C			120		nC
C _T	Junction Capacitance V _R = 1V, T _J = 25°C, f = 1MHz			630		pF
	Junction Capacitance V _R = 200V, T _J = 25°C, f = 1MHz			115		
	Junction Capacitance V _R = 400V, T _J = 25°C, f = 1MHz			85		

THERMAL AND MECHANICAL CHARACTERISTICS

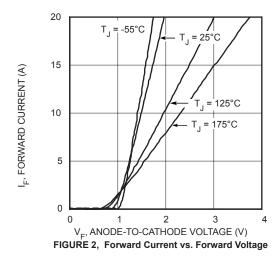
Symbol	Characteristic / Test Conditions	Min	Тур	Max	Unit
$R_{\theta JC}$	Junction-to-Case Thermal Resistance			0.9	°C/W
W _T	Package Weight		0.22		oz
			5.9		g
Torque	Maximum Mounting Torque			10	lb∙in
				1.1	N·m

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TYPICAL PERFORMANCE CURVES



RECTANGULAR PULSE DURATION (seconds)
FIGURE 1. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION



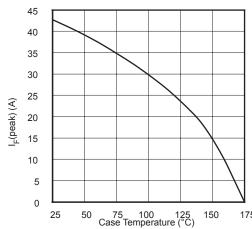


FIGURE 3, Maximum Forward Current vs. Case Temperature

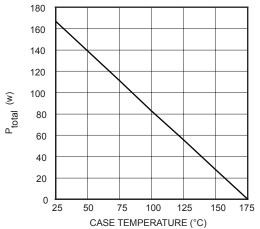
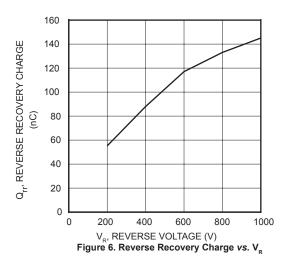


Figure 4. Maximum Power Dissipation vs. Case Temperature



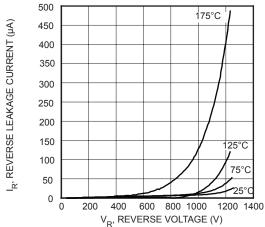
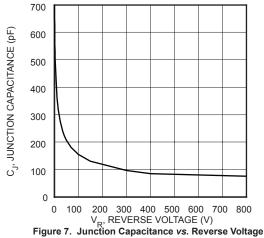
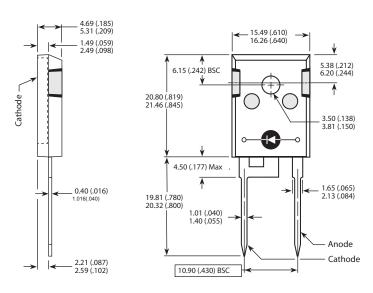


Figure 5. Reverse Leakage Currents vs. Reverse Voltage



TO-247 Package Outline



Dimensions in Millimeters and (Inches)

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